Pall Corporation

Mega-Etch Filter

Description

The Mega-Etch filter has been designed for HF and BOE recirculation bath processing. The patented highly asymmetric polysulfone membrane enables very high flow rates and fine filtration with minimal demand on limited pumping capacity. The end result is fast starts, excellent particle retention, low microbubble potential, and superior bath quality.

When operated at ambient temperature, the Mega-Etch filter is compatible with a wide range of etch solutions and semiaqueous strippers that are primarily HF based[1]. It is highly recommended for use in SiO_2 etch with surfactant and low horsepower internal pumps. For spontaneous wetting in high surface tension fluid, the Fluorodyne filter can be used.

[1] The Mega-Etch filter should be tested before installation to determine compatibility.

Features

- Excellent retention
- Very high flow rates
- Rapid bath turnover
- Low extractable
- Utlralow metal Ion extractables option
- No prewetting with IPA required
- Manufactured in a clean room environment
- 100 % integrity tested

Specifications

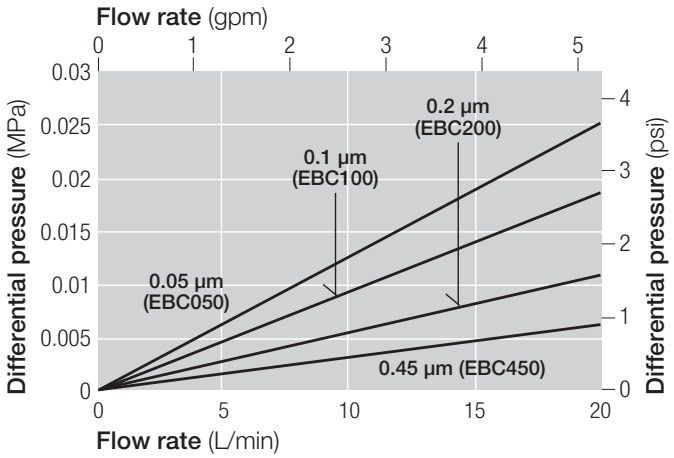
Materials of Construction

Components	Materials
Filter Medium	Highly asymmetric hydrophilic polysulfone
Media Support	Polypropylene
Core / Outer Cage	Polypropylene
End Caps	Polypropylene
O-ring	Fluoroelastomer (standard)

Removal Ratings and Operating Conditions

Removal Ratings	0.45 µm (0.1 µm Recirculating Performance), 0.2 µm, 0.1 µm, 0.05 µm
Nominal Length	254 mm / 10", 508 mm / 20"
Diameter	66 mm / 2.6 "
Nominal Filter Area	254 mm / 10" – 0.65 m^2 / 7.0 ft^2 508 mm / 20" – 1.30 m^2 / 14.0 ft^2
Maximum Operating Temperature	95 °C / 203 °F
Maximum Forward Differential Pressure	0.34 MPaG @ 20 °C / 50 psig @ 60 °F

Pressure Drop vs. Liquid Flow Rate[2] (Water, 20°C)



[2] For liquids with viscosity differing from water, multiply the pressure drop by the viscosity in centipoise.
Unit conversion : 1 MPa = 10 bar

Part Numbers / Ordering Information

EBC 1 2 3 4

Table 1

Code	Removal Ratings (µm)
050	0.05
100	0.1
200	0.2
450	0.45 (0.1 RP)

Table 2

Code	Cartridge Lengths
10	254 mm / 10 in
20	508 mm / 20 in

Table 3

Code	End Configurations
M3	SOE flat closed end; external 222 O-rings
M7	SOE fin end; external 226 O-rings
M8	SOE fin end; external 222 O-rings

Table 4

Code	End Configurations
V	Fluoroelastomer (standard)
T	FEP encapsulated silicone
F	FEP encapsulated fluoroelastomer
C	Chemraz[3]

[3] Chemraz is a registered trademark of Greene Tweed and Co.

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